

H5N2005DL, H5N2005DS

Silicon N Channel MOS FET High Speed Power Switching

REJ03G1104-0200

(Previous: ADE-208-1373)

Rev.2.00 Sep 07, 2005

Features

- Low on-resistance
- Low drive current
- High speed switching

Outline





Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	200	V
Gate to source voltage	V_{GSS}	±30	V
Drain current	I _D	6	Α
Drain peak current	I _D (pulse) Note 1	24	Α
Body-drain diode reverse drain current	I _{DR}	6	Α
Body-drain diode reverse drain peak current	I _{DR (pulse)} Note 1	24	Α
Channel dissipation	Pch Note 2	25	W
Channel to case thermal Impedance	θ ch-c	5	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at Tc = 25°C

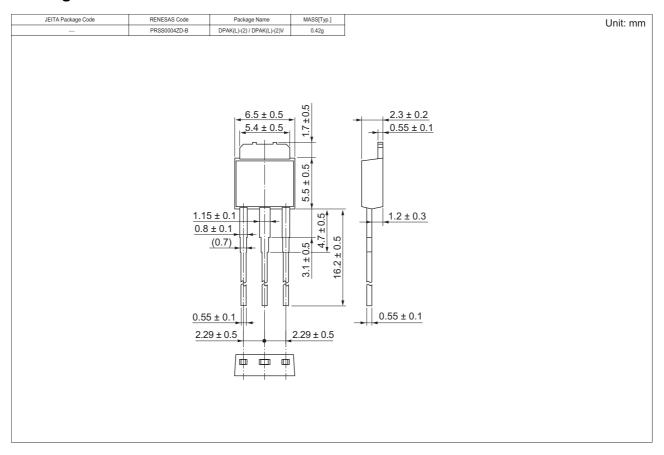
Electrical Characteristics

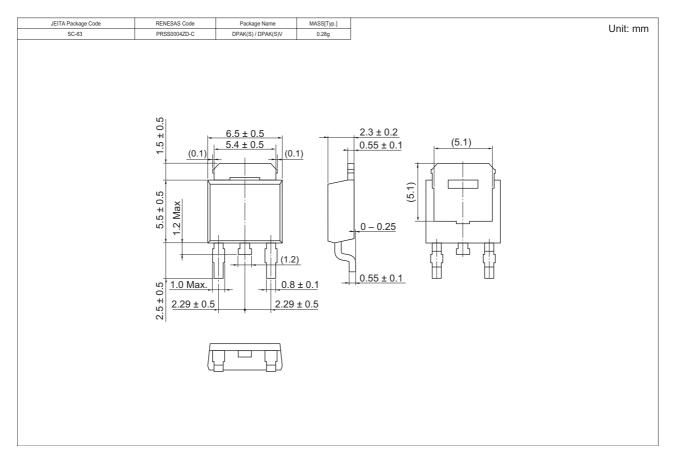
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	200		_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_		±0.1	μΑ	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}		_	1	μΑ	$V_{DS} = 200 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	3.0	_	4.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Static drain to source on state resistance	R _{DS (on)}	_	0.52	0.65	Ω	$I_D = 3 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note 3}}$
Forward transfer admittance	y _{fs}	2.0	3.4	_	S	$I_D = 3 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss	_	300	_	pF	V _{DS} = 25 V
Output capacitance	Coss	_	44	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	12.5	_	pF	f = 1 MHz
Total gate charge	Qg	_	9.8	_	nC	V _{DD} = 160 V
Gate to source charge	Qgs	_	2.0	_	nC	V _{GS} = 10 V
Gate to drain charge	Qgd	_	5.2	_	nC	$I_D = 6 A$
Turn-on delay time	t _{d (on)}	_	23	_	ns	I _D = 3 A
Rise time	t _r	_	24	_	ns	V _{GS} = 10 V
Turn-off delay time	t _{d (off)}	_	43.5	_	ns	$R_L = 33.3 \Omega$
Fall time	t _f	_	11	_	ns	$Rg = 10 \Omega$
Body-drain diode forward voltage	V_{DF}	_	1.0	1.5	V	I _F = 6 A, V _{GS} = 0
Body-drain diode reverse recovery time	t _{rr}	_	90	_	ns	I _F = 6 A, V _{GS} = 0
Body-drain diode reverse recovery charge	Qrr		400		nC	di _F /dt = 100 A/μs

Note: 3. Pulse test

Package Dimensions





H5N2005DL, H5N2005DS

Ordering Information

Part Name	Quantity	Shipping Container
H5N2005DL-E	3200 pcs	Box (Sack)
H5N2005DSTL-E	3000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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